

**THERMAL DISSIPATION ASSEMBLY EMPLOYING
THERMOELECTRIC MODULE WITH MULTIPLE ARRAYS OF
THERMOELECTRIC ELEMENTS OF DIFFERENT DENSITIES**

Abstract of the Disclosure

A thermoelectric assembly is provided for an electronic device, having a surface with a non-uniform thermal distribution between at least one first region and at least one second region, with the at least one first region having a higher heat flux than the at least one second region. The assembly includes at least one first area of thermoelectric elements and at least one second area of thermoelectric elements, which are configured to align over the at least one first region of higher heat flux, and the at least one second region, respectively, when the assembly is coupled to the device. The at least one first area of thermoelectric elements includes a greater density of thermoelectric elements than the at least one second area of thermoelectric elements for handling the higher heat flux.